



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL05C4R7CB5NNNC
- Description : CAP, 4.7pF, 50V, ±0.25pF, C0G, 0402

A. Samsung Part Number

	<u>CL</u>	<u>05</u> <u>C</u>	<u>4R7</u> <u>C</u>	<u>B</u>	<u>5</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>c</u>
	1	23	4 (5) (6)		8	9	10	1
① Series	Samsung Multi-layer Ceramic Capacitor								
② Size	0402 (inch co	ode)	L: 1.	0 ± 0.0)5	mm		W:	0.5 ± 0.05 mm
③ Dielectric	C0G		8	Inne	r ele	ctrod	e		Ni
Capacitance	4.7 pF			Tern	ninat	ion			Cu
⑤ Capacitance	±0.25 pF			Plati	ng				Sn 100% (Pb Free)
tolerance			9	Proc	luct				Normal
6 Rated Voltage	50 V		10	Spee	cial				Reserved for future use
⑦ Thickness	0.5 ± 0.05	mm	1	Pack	kagin	ıg			Cardboard Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	494 min						
Insulation	10,000Mohm or 500Mohm ⋅ μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!\!\!\mathrm{C}$ to 125 $^\circ\!\!\!\mathrm{C}$, Capacitance change shoud be within ±30PPM/ $^\circ\!\!\!\mathrm{C}$)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10 H_z to 55 H_z (return : 1min.)				
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)				
Moisture	Capacitance change :	With rated voltage				
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q : 115.67 min					
	IR : 500Mohm or 25Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature				
	Q : 247 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm $\cdot \mu F$					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperatur \rightarrow 25 °C				
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^\circ\!\mathrm{C}$				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.